electrophotographic printer, and to a method of assembling the optical write head.

Please amend the paragraph bridging pages 4 and 5, starting at line 25 of page 4 and ending at line 4 of page 5, as follows:

The mechanical components must be formed into [complicate] complicated shapes, by means of ensuring, for example, a space for effecting alignment of an optical axis. Such complicated working of the mechanical components is a contributory factor to hindering a reduction in manufacturing costs of an optical write head.

Please amend the paragraph on page 20, at lines 8-20, as follows:

A reference plane A of the support member 140 is a precision-machined plane. The rod lens array 111 is positioned in the thicknesswise direction thereof, by means of bringing a frame 126 of the rod lens array 111 into close contact with the reference plane A. However, FRP is usually employed for the frame 126 of the rod lens array 111, and the frame 126 has a thickness precision of about ±0.4 mm. Such thickness precision accounts for the occurrence of variations in distance from the outer surface of the frame to the center of the [of the] rod lens. In addition, orientation of glass fibers of FRP results in irregularities arising in the surface of FRP. Even at the time of manufacture of a rod lens array, the row of rod lenses is disarranged when rod lenses are arranged on an FRP plate.

Please amend the paragraph on page 28, at lines 5-24, as follows:

A two-layer FPC substrate (film or sheet) 257 has copper-foil wiring patterns 261 sandwiched between resin layers 258 formed from heat-resisting resin, such as polyimide. The FPC substrate 257 is bonded to a metal block 251 formed from metallic material, by means of a thermosetting adhesive 365 (see Fig. 8). The number of layers of FPC substrates 257 may be increased, as necessary. Self-scan-type light-emitting device array chips 250 are mounted into a row and at predetermined locations on the surface of copper foil 262 laid on the surface of the

FPC substrate bonded to the metal block 251. The array chips 250 are arranged by means of a die bonder and fixed by means of a conductive adhesive. Fig. 6 shows an example in which the array chips 250 are arranged in a staggered layout. However, the array chips 250 can be arranged in a straight line. Before the FPC substrate 257 is assembled into an optical write head, electrode pads 258 provided on the light-emitting array chips 250 having the light-emitting devices 252 mounted thereon are electrically connected, by means of wire bonding, to conductor pads [265] 270 located at predetermined locations within an area 267 of the FPC substrate 257 from which a resin layer has been partially removed.

In the Claims:

Please amend claims 1, 3, 5, 6, 8-11, 15, and 30-31 (clean copies of the amended and new claims are attached in Appendix 2):

Claim 1 (once amended). An optical write head comprising a substrate, and a plurality of light-emitting device array chips arranged on the substrate in a straight line or in a staggered layout so as to oppose a [gradient index] rod lens array, each of the light-emitting array device chips having a light-emitting device array, wherein the rod lens array, a substrate support member for supporting the substrate, and a driver circuit board are [fixedly held by] each secured directly to a support member.

Claim 3 (once amended). The optical write head according to claim 1, wherein at least one [of frames] frame of the rod lens array to be bonded to [a] said support member is a glass plate.

Claim 5 (once amended). The optical write head according to claim 1, wherein at least one slit of V-shaped cross section for injecting an adhesive is formed in a portion of [the] a surface of the support member to be brought into contact with the rod lens array, so as to extend in the longitudinal direction of the rod lens array, and a plurality of adhesive injection holes are formed in the at least one slit so as to penetrate through the support member to a reverse side thereof.